

DIALOG(R)File 352:Derwent WPI

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XRAM Acc No: C1994-032207

XRPX Acc No: N1994-056118

Multilayered package for food, esp. retort food - includes layer comprising ethylene@l-vinyl ester copolymers and polyamide, between resin layers

Patent Assignee: KURARAY CO LTD (KURS)

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Patent Family (1 patents, 1 countries)

Patent			Application			
Number	Kind	Date	Number	Kind	Date	Update
JP 6023924	A	19940201	JP 1992207499	A	19920710	199409 B

Priority Applications (no., kind, date): JP 1992207499 A 19920710

Patent Details

Number	Kind	Lan	Pg	Dwg	Filing Notes
JP 6023924	A	JA	7	0	

Alerting Abstract JP A

Package includes: (1) a resin outer layer having a water vapour permeability (measured at 40 deg.C and 90% relative humidity) of at least 40 g/m².day; (2) an interlayer comprising (A) 96-50 wt.% saponified ethylene-vinyl ester copolymer having an ethylene content of 20-60 mols %; (B) 3-49 wt.% polyamide; and (C) 1-45 wt.% saponified ethylene-vinyl ester copolymer having an ethylene content of at least 4 mols % higher than that of (A) resin; and (3) a resin inner layer having a water vapour permeability (measured at 40 deg.C and 90% relatively humidity) of up to 20 g/m².day.

USE/ADVANTAGE - The multilayered package is used in packaging a food, partic. a retort food. The package has good hot water resistance and a less usual appearance caused by bending during retort or immediately after retort, and reduced deterioration in gas barrier by retort.

Title Terms /Index Terms/Additional Words: MULTILAYER; PACKAGE; FOOD;
RETORT
; LAYER; COMPRISE; POLYETHYLENE; POLYVINYL; POLYESTER; COPOLYMER;
POLYAMIDE; RESIN

Class Codes

International Classification (Main): B32B-027/28
(Additional/Secondary): B65D-065/40, C08L-023/08, C08L-077/00

File Segment: CPI; EngPI

DWPI Class: A17; A23; A92; P73; Q34

Manual Codes (CPI/A-M): A05-F01E3; A09-A09; A10-E09; A12-P01B

Chemical Indexing

Plasdoc Codes (KS): 0218 0231 0241 0782 1283 2006 2007 2008 2513
2600 2604 2609 2680 2726 2774 2780 3256

Polymer Fragment Codes (PF):

001 017 04- 331 381 435 443 477 540 541 542 549 58& 633

002 017 034 04- 040 041 046 047 066 141 231 244 245 27& 331 381 435 443
477 541 542 549 633 722

Specific Compound Numbers: R00326; R00326

Derwent Chemistry Resource Numbers: (Linked) 1013-DIS; 1013; 1013

Key Word Indexing

1 1013-DIS

Polymer Indexing

<01>

001 017; P0000; S9999 S1285-R

002 017; ND01; Q9999 Q7818-R; Q9999 Q8366-R; Q9999 Q7589-R; B9999 B4682
B4568; B9999 B4706-R B4568; K9574 K9483; K9698 K9676; B9999 B3758-R
B3747

003 017; B9999 B4875 B4853 B4740; K9712 K9676

<02>

001 017; G0566-R G0022 D01 D12 D10 D51 D53 D58 D63 F41; G0044 G0033
G0022

D01 D02 D12 D10 D51 D53 D58 D82 R00326-R 1013-R; H0022 H0011; S9999
S1285-R; P1150

002 017; G0566-R G0022 D01 D12 D10 D51 D53 D58 D63 F41; G0044 G0033
G0022

D01 D02 D12 D10 D51 D53 D58 D82 R00326-R 1013-R; H0022 H0011; S9999
S1285-R; M9999 M2313; P1694-R; P1150

003 017; P0635-R F70; S9999 S1285-R

004 017; ND01; Q9999 Q7818-R; Q9999 Q8366-R; Q9999 Q7589-R; B9999 B4682
B4568; B9999 B4706-R B4568; K9574 K9483; K9698 K9676; B9999 B3758-R
B3747

005 017; K9745-R

Original Publication Data by Authority

Japan

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****MULTI-LAYERED PACKAGING MATERIAL****

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